



# ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C8M16MSA-6BIN								
Part Weight:		101.157mg								
NO	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	G1250	57.595	Epoxy Resin	Resin		5.500%	3.168	3.1315%	31,315
				Phenol resin	Resin		4.500%	2.592	2.5621%	25,621
				Silica(Fused)	filler	60676-86-0	89.700%	51.663	51.0718%	510,718
				Carbon Black	Additive	1333-86-4	0.300%	0.173	0.1708%	1,708
2	Substrate	BT	28.815	832NX-A	Core		46.130%	13.292	13.1403%	131,403
				AUS308	Mask		13.750%	3.962	3.9167%	39,167
				Cu	Trace	7440-50-8	39.370%	11.344	11.2147%	112,147
				Ni	plating	7440-02-0	0.660%	0.190	0.1880%	1,880
				Au	plating	7440-57-5	0.090%	0.026	0.0256%	256
3	DAF	EM700	0.577	Solid Epoxy Resin	Base material		12.500%	0.072	0.0713%	713
				Phenol Resin	Base material		12.500%	0.072	0.0713%	713
				Fused Silica	Base material	60676860	35.000%	0.202	0.1996%	1,996
				Synthrtic Rubber	Base material		40.000%	0.231	0.2282%	2,282
4	Wire	Ag0.8mil	0.457	Ag	Base material	7440-22-4	89.100%	0.407	0.4025%	4,025
				Au	Base material	7440-57-5	7.400%	0.034	0.0334%	334
				Pd	Base material	7440/5/3	3.500%	0.016	0.0158%	158
5	Solder Ball	M705	8.971	Tin (Sn)	Base material	7440-31-5	96.500%	8.657	8.5580%	85,580
				Ag	Base material	7440-22-4	3.000%	0.269	0.2661%	2,661
				Cu	Base material	7440-50-8	0.500%	0.045	0.0443%	443
6	Die	0.12mm	4.742	Si	Chip	7440-21-3	100.000%	4.742	4.6878%	46,878
								101.157	100.0000%	1,000,000